

Computer Organization and Architecture

Internal Organization of Memory Chips : DRAM

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Recap

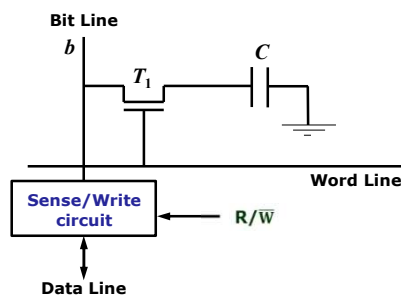
- Memory design
- Internal organization of memory
- SRAM chip design
- SRAM module design

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Dynamic RAM (DRAM) Cell

- Less expensive and simpler cell
- Information is stored in the form of a charge on a capacitor (C)
 - Charge in capacitor is stored only for short time
 - However, a cell is required to store information for a much longer time
- To retain information for longer time, content of capacitor must be periodically refreshed



- Low speed as refresh needed
- Only 1 transistor is used
- Used to build **main memory**

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Dynamic RAM (DRAM) Chip Organization

- DRAM cells are also arranged in 2-dimensional array form
- Here also, **row address lines** are used to select row and **column address lines** are used to select column
- **Two important factors** influence the design of the DRAM chip are:
 - **Number of input/output pins i.e. external pins**
 - **Need to refresh the cells**
- Scheme for saving pins:
 - Row address and column address are **transmitted over the same line** one after the other
 - This is called **time multiplexing**
 - This is usually performed by a **memory controller circuit**
 - It generates the different control signals

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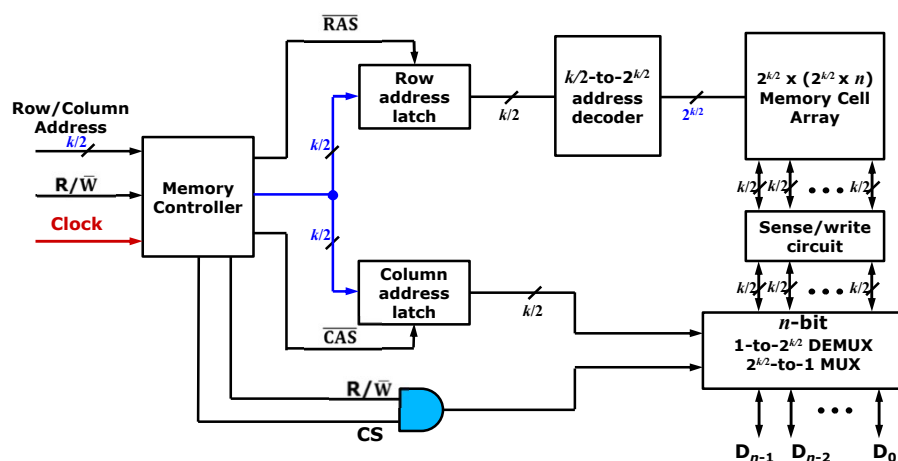
Dynamic RAM (DRAM) Chip Organization

- Two additional control signals are needed to inform the chip when the row address and column address is valid on address line
 - Row address strobe ($\overline{\text{RAS}}$):
 - Inform the chip when the row address is valid on address lines
 - Column address strobe ($\overline{\text{CAS}}$):
 - Inform the chip when the column address is valid on address lines
 - Both $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ are usually active low

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DRAM Chip Organization



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DRAM Chip Organization

- During read or write operation, the row address is applied first
 - It is loaded into row address latch in response to \overline{RAS}
 - Then read operation is initiated, in which all cells in a selected row are read and refreshed
- Shortly after row address is loaded, the column address is applied
 - It is loaded onto the column address latch under the control of \overline{CAS}
- The information in the column address latch is decoded and appropriate n sense/write circuits are selected
- To ensure that the contents of DRAM are maintained, each row of cells must be accessed and refreshed periodically

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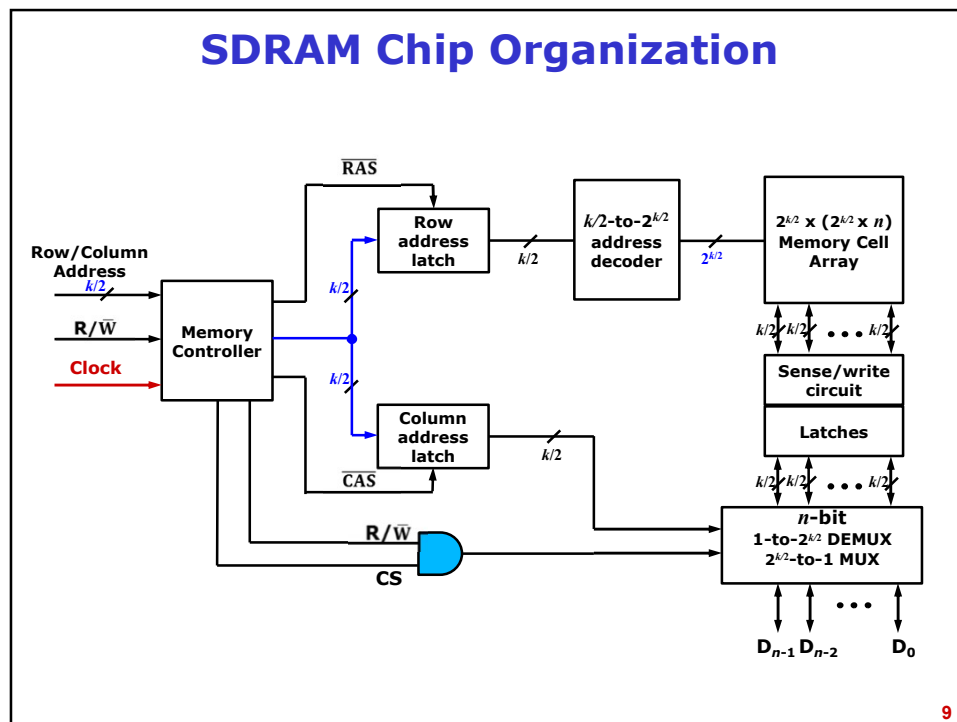
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DRAM Chip Organization

- Memory controller circuit provide the necessary signals \overline{CAS} and \overline{RAS} that governs timing
- These operations are directly synchronised with clock signal
- Such a DRAM chip is called Synchronous DRAM (SDRAM)

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Fast Page (Burst) Mode Feature of SDRAM

- Transfer capability of SDRAM
- Contents of all $2^{k/2}$ cells in a selected row are sensed in each on the n cell arrays
- Only n bits (one from each of the cells arrays) are placed in the data lines, $D_{(n-1)-0}$
- To access other bytes in the same row, without having to reselect the row, a latch is used at the output of the sense/write circuits in each column
- The row address will load the latches corresponding to all bits in the selected row
- Then different column address are applied to place the different bytes on data lines
- Transfer bytes in sequential order
- This arrangement allows transferring a block of data at much faster rate

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Refresh Overhead in SDRAM

- All dynamic memories need to be refreshed
- In SDRAM typical period of refreshing all rows is **64ms**
- Each row is refreshed at least in 64ms
- **Example:**
 - Suppose a SDRAM chip has 8K (8192) rows
 - Number of clock cycles to access each row: 4 clock cycles
 - Number of clock cycles to refresh all rows:
 $8192 \times 4 = 32768$ clock cycles
 - Suppose clock rate of SDRAM is 133 MHz
 - Times needed to refresh all rows:
 $32768 / 133 \times 10^6 = 246 \times 10^{-6} \text{ s} = 0.246 \text{ ms}$
 - **Refreshing overhead is 0.246ms out of 64ms**

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Memory Performance Parameters

- **Access Time:**
 - Time interval between initiation of one operation and completion of that operation
 - **Example:** Time between assertion of Read signal and MFC signal
- **Memory Cycle Time:**
 - Minimum time delay between the initiation of two successive memory operations
 - Time delay between start of a read/write operation to start of next memory operation
- Memory cycle time is usually slightly larger than access time

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Memory Performance Parameter: Memory Latency

- **Latency:** Amount of time it takes to transfer a word of data to or from the memory
 - While reading and writing single word of data, latency provides a complete indication of memory performance
- In burst operations the time needed to complete the operations depends also on the rate at which successive words can be transferred
- **Latency(block transfers):** Time to access the first of the sequence of memory words
 - How much time needed to transfer the entire block
 - Blocks are of varying size
 - Number of bits or bytes that can be transferred in one second

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Memory Bandwidth

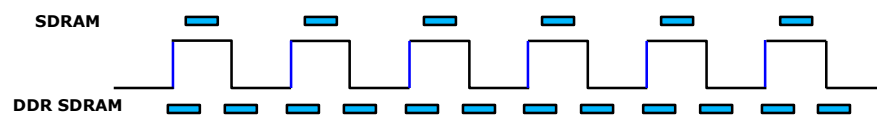
- **Number of bits or bytes that can be transferred in one second**
 - Depends on the speed of access to the stored data
 - Also depends on the number of bits that can be accessed in parallel
- **Effective bandwidth in a computer**
 - Speed of memory
 - Transfer capability of the links that connect the memory and the processor—speed of bus

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Double-Data-Rate SDRAM (DDR SDRAM)

- Faster version of SDRAM
- The standard SDRAM performs all actions on the raising edge of the clock cycle
- DDR SDRAM access the cell array in the same way, but transfers the data on both edges of the clock
- Hence, their bandwidth is essentially doubled for long burst transfers
- **Bandwidth**: The number of bits/bytes that can be transferred in one second



BM 33L5039 RAM Module
(1 GB, DDR RAM, 266 MHz, DIMM 184-pin)



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Reference

- Carl Hamacher, Zvonko Vranesic and Safwat Zaky, "Computer Organization", 5th Edition, Tata McGraw Hill, 2002

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Thank You

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